



# bq4847/bq4847Y

## RTC Module With CPU Supervisor

### Features

- Real-Time Clock counts seconds through years in BCD format
- Integrated battery and crystal
- On-chip battery-backup switch-over circuit with nonvolatile control for an external SRAM
- 130mAh battery capacity
- $\pm 1$  minute per month clock accuracy
- Less than 500nA of clock operation current in backup mode
- Microprocessor reset valid to  $V_{CC} = V_{SS}$
- Independent watchdog timer with a programmable time-out period
- Power-fail interrupt warning
- Programmable clock alarm interrupt active in battery-backup mode
- Programmable periodic interrupt
- Battery-low warning

### General Description

The bq4847 Real-Time Clock Module is a low-power microprocessor peripheral that integrates a time-of-day clock, a 100-year calendar, a CPU supervisor, a battery, and a crystal in a 28-pin DIP module. The part is ideal for fax machines, copiers, industrial control systems, point-of-sale terminals, data loggers, and computers.

The bq4847 contains an internal battery and crystal. Through the use of the conditional chip enable output ( $\overline{CE_{OUT}}$ ) and battery voltage output ( $V_{OUT}$ ) pins, the bq4847 can write-protect and make nonvolatile an external SRAM. The backup cell powers the real-time clock and maintains SRAM information in the absence of system voltage.

The bq4847 contains a temperature-compensated reference and comparator circuit that monitors the status of its voltage supply. When an out-of-tolerance condition is detected, the bq4847 generates an interrupt warning and subsequently a microprocessor reset. The reset stays active for 200ms after  $V_{CC}$  rises within

tolerance to allow for power supply and processor stabilization.

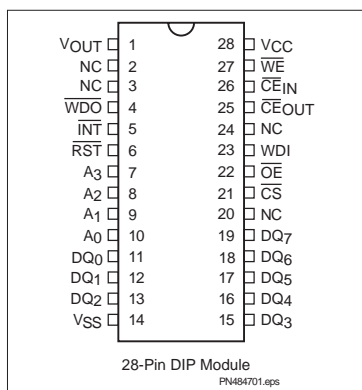
The bq4847 also has a built-in watchdog timer to monitor processor operation. If the microprocessor does not toggle the watchdog input (WDI) within the programmed time-out, the bq4847 asserts  $\overline{WDO}$  and  $\overline{RST}$ . WDI unconnected disables the watchdog timer.

The bq4847 can generate other interrupts based on a clock alarm condition or a periodic setting. The alarm interrupt can be set to occur from once per second to once per month. The alarm can be made active in the battery-backup mode to serve as a system wake-up call. For interrupts at a rate beyond once per second, the periodic interrupt can be programmed with periods of 30.5 $\mu$ s to 500ms.

### Caution:

Take care to avoid inadvertent discharge through  $V_{OUT}$  and  $\overline{CE_{OUT}}$  after battery isolation has been broken.

### Pin Connections



### Pin Names

$A_0-A_3$	Clock/Control address inputs	NC	No connect
$DQ_0-DQ_7$	Data inputs/outputs	$V_{OUT}$	Back-up battery output
$\overline{WE}$	Write enable	$\overline{INT}$	Interrupt output
$\overline{OE}$	Output enable	$\overline{RST}$	Microprocessor reset
$\overline{CS}$	Chip select input	WDI	Watchdog input
$\overline{CE_{IN}}$	External RAM chip enable	$\overline{WDO}$	Watchdog output
$\overline{CE_{OUT}}$	Conditional RAM chip enable	$V_{CC}$	+5V supply
		$V_{SS}$	Ground

## bq4847/bq4847Y

### Functional Description

Figure 1 is a block diagram of the bq4847. The bq4847 is functionally equivalent to the bq4845 except that the battery (20, 24) and crystal (2, 3) pins are not accessible. The pins are connected internally to a coin cell and quartz crystal. The coin cell provides 130mAh of capacity. It is internally isolated from  $V_{OUT}$  and  $\overline{CE}_{OUT}$  until the initial application of  $V_{CC}$ . Once  $V_{CC}$  rises above  $V_{PFD}$ , this isolation is broken, and the backup cell provides power to  $V_{OUT}$  and  $\overline{CE}_{OUT}$  for the external SRAM. The real-time clock keeps time to within one minute per month at

room temperature. For a complete description of features, operating conditions, electrical characteristics, bus timing, and pin descriptions, see the bq4845 data sheet. Valid part types for ordering are bq4847MT (5%) and bq4847YMT (10%).

Figure 2 illustrates the address map for the bq4847. Table 1 is a map of the bq4847 registers, and Table 2 describes the register bits.

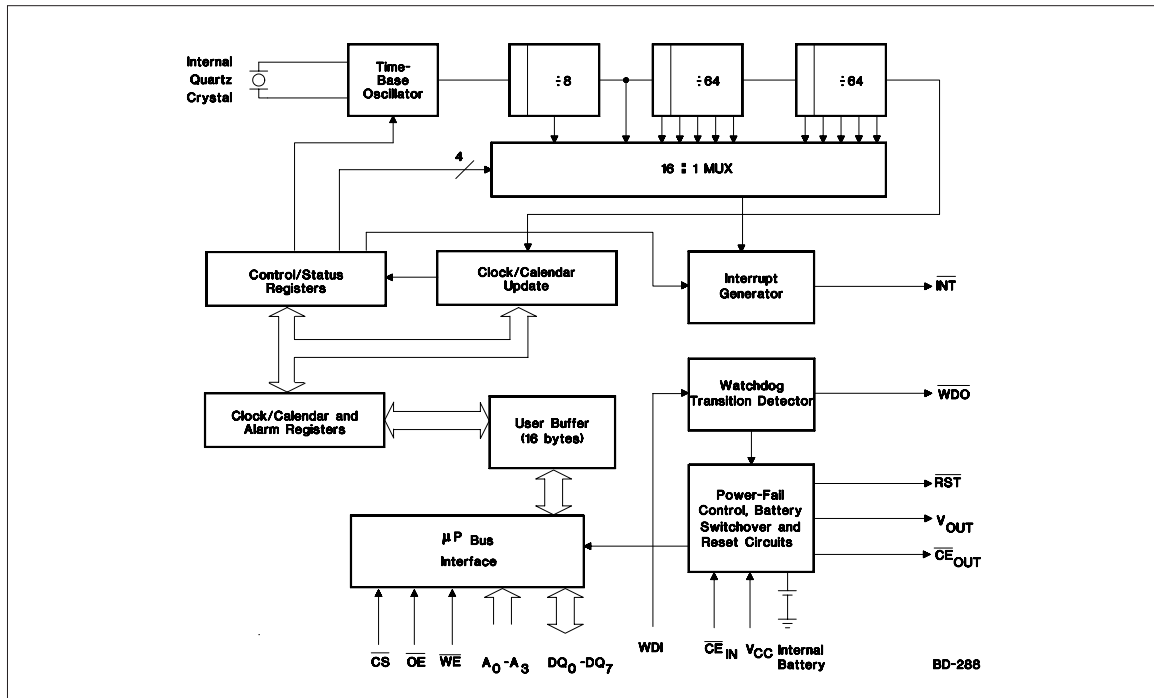


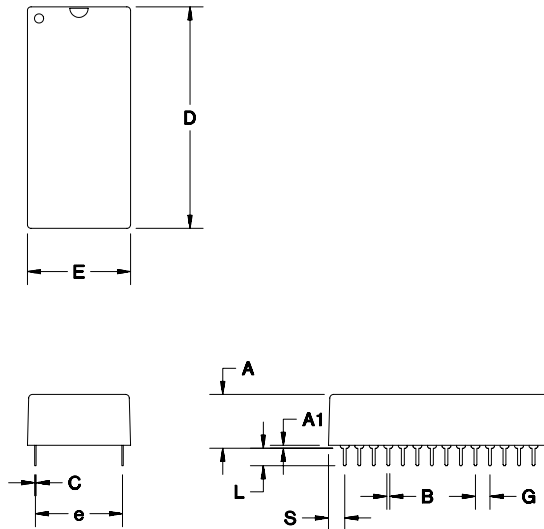
Figure 1. Block Diagram

### Truth Table

$V_{CC}$	$\overline{CS}$	$\overline{OE}$	$\overline{WE}$	$\overline{CE}_{OUT}$	$V_{OUT}$	Mode	DQ	Power
$< V_{CC} \text{ (max.)}$  $> V_{CC} \text{ (min.)}$	$V_{IH}$	X	X	$\overline{CE}_{IN}$	$V_{OUT1}$	Deselect	High Z	Standby
	$V_{IL}$	X	$V_{IL}$	$\overline{CE}_{IN}$	$V_{OUT1}$	Write	$D_{IN}$	Active
	$V_{IL}$	$V_{IL}$	$V_{IH}$	$\overline{CE}_{IN}$	$V_{OUT1}$	Read	$D_{OUT}$	Active
	$V_{IL}$	$V_{IH}$	$V_{IH}$	$\overline{CE}_{IN}$	$V_{OUT1}$	Read	High Z	Active
$< V_{PFD} \text{ (min.)} > V_{SO}$	X	X	X	$V_{OH}$	$V_{OUT1}$	Deselect	High Z	CMOS standby
$\leq V_{SO}$	X	X	X	$V_{OHB}$	$V_{OUT2}$	Deselect	High Z	Battery-backup mode

## bq4847/bq4847Y

### MT: 28-Pin T-Type Module



28-Pin MT (T-Type Module)

Dimension	Inches		Millimeters	
	Min.	Max.	Min.	Max.
A	0.360	0.390	9.14	9.91
A1	0.015	-	0.38	-
B	0.015	0.022	0.38	0.56
C	0.008	0.013	0.20	0.33
D	1.520	1.535	38.61	38.99
E	0.710	0.740	18.03	18.80
e	0.590	0.620	14.99	15.75
G	0.090	0.110	2.29	2.79
L	0.110	0.130	2.79	3.30
S	0.100	0.120	2.54	3.05

### Ordering Information

**bq4847 - MT**

**Package Option:**

MT = 28-pin T-type Module

**Voltage Tolerance:**

Blank = 5%

Y = 10%

**Device:**

bq4847 Real-Time Clock Module With CPU Supervisor

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
BQ4847MT	LIFEBUY	DIP MODULE	MT	28	13	Pb-Free (RoHS)	Call TI	N / A for Pkg Type	0 to 70		
BQ4847YMT	LIFEBUY	DIP MODULE	MT	28		TBD	Call TI	Call TI	0 to 70		

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

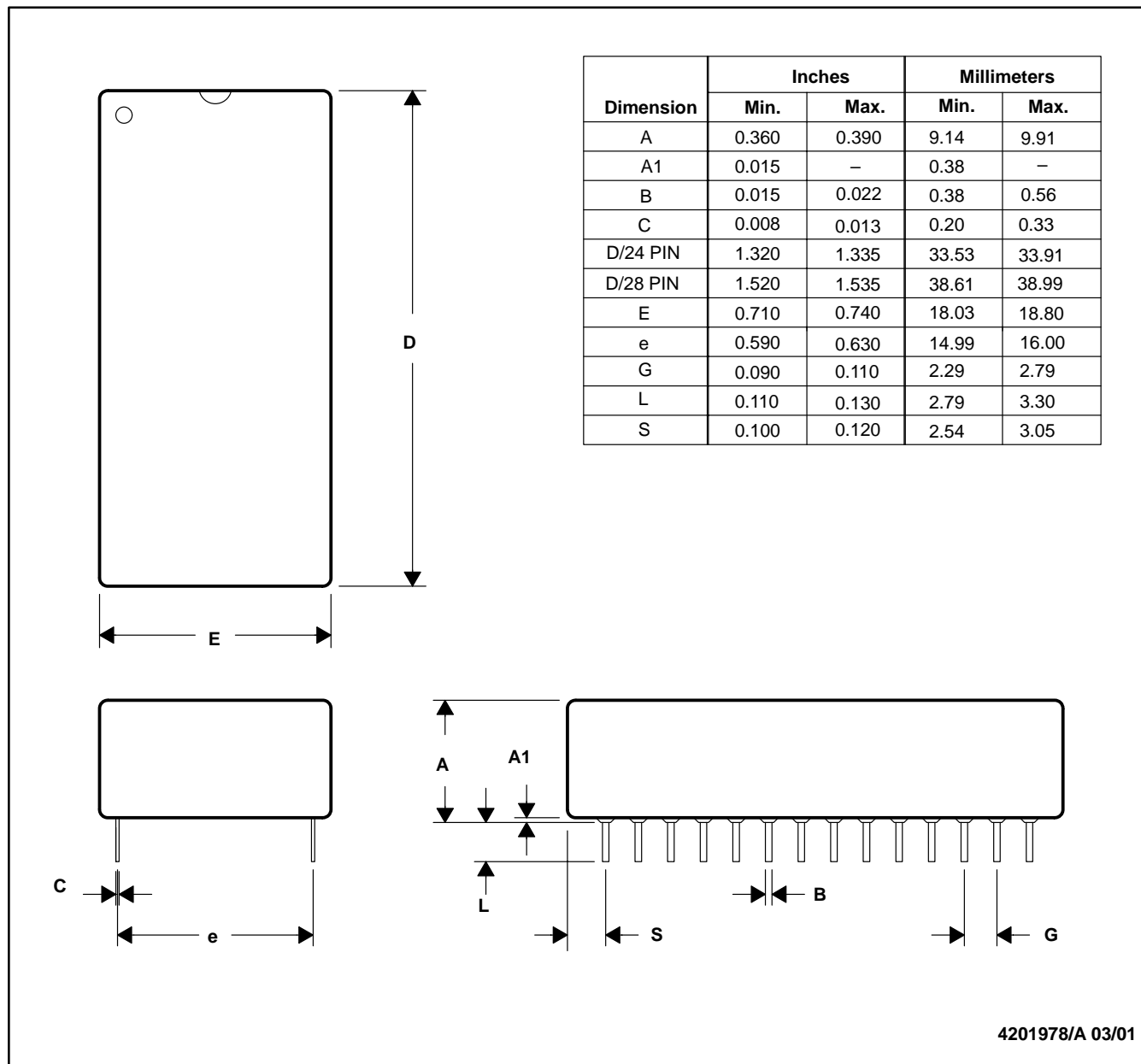
**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## MT (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (mm).  
 B. This drawing is subject to change without notice.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)